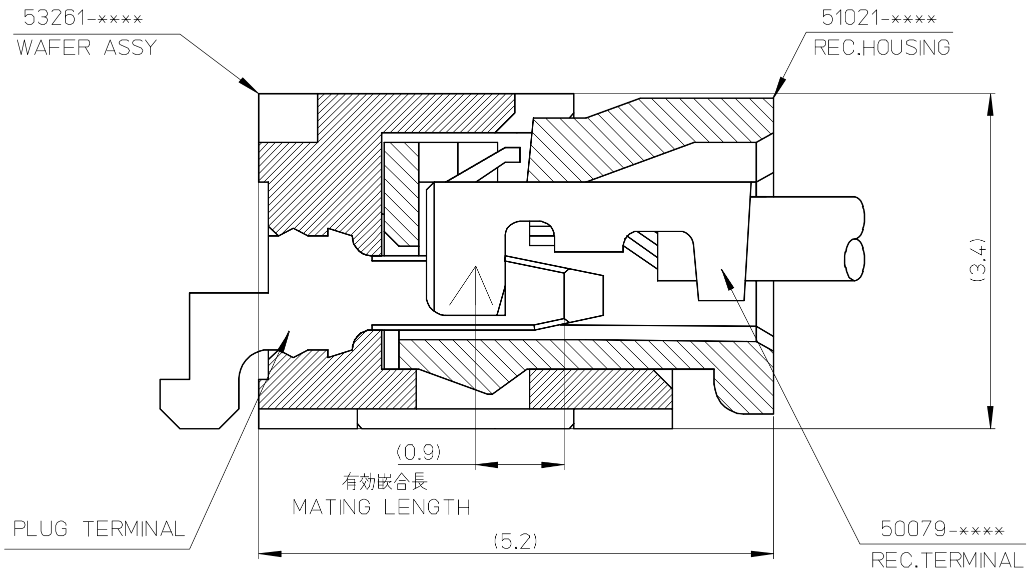


53261-∗∗∗∗	WAFER ASSY		MODEL NO./MATERIAL NO.
50079-∗∗∗∗	TERMINAL	REC.	
51021-∗∗∗∗	HOUSING		

RELEASED
EC NO: J2006-2426
DRWN:YAOYAGI 2006/02/02
CH'KD:YMAEDA 2006/02/03
APPR:NUKITA 2006/02/07
DESCRIPTION
0
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	± ---
10 OVER 30 UNDER	± ---
30 OVER	± ---
ANGULAR ± --- °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	DATE
Y.AOYAGI	2006/01/30
CHECKED BY	DATE
Y.MAEDA	2006/01/30
APPROVED BY	DATE
N.UKITA	2006/01/30

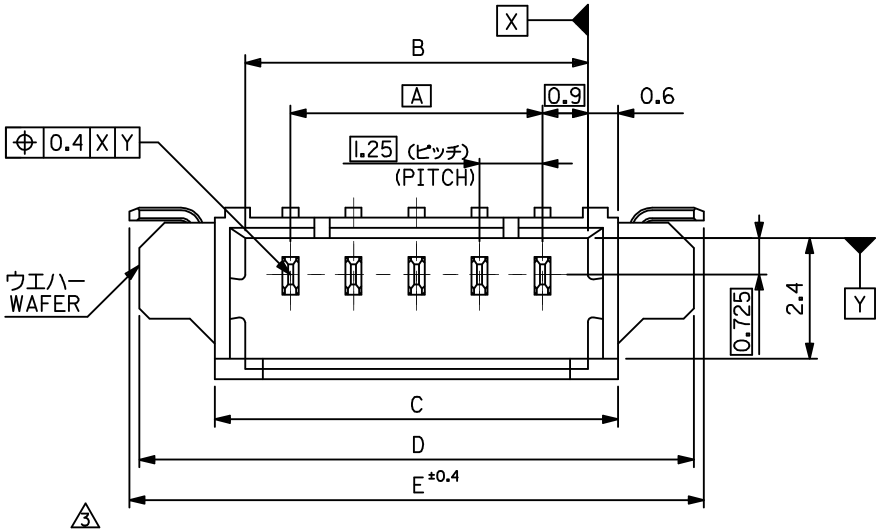
TITLE

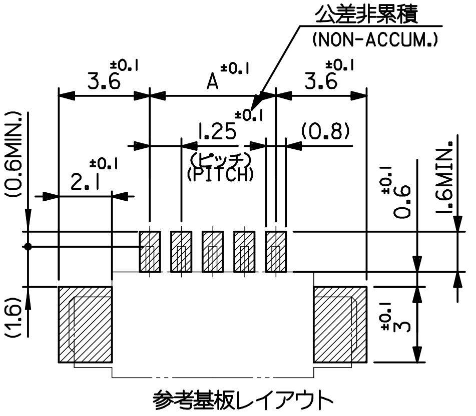
1.25 W-TO-B CONN.
51021,53261
MATING CROSS SECTION

MOLEX INCORPORATED

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
SEE CHART	SD-51021-002	1 OF 1

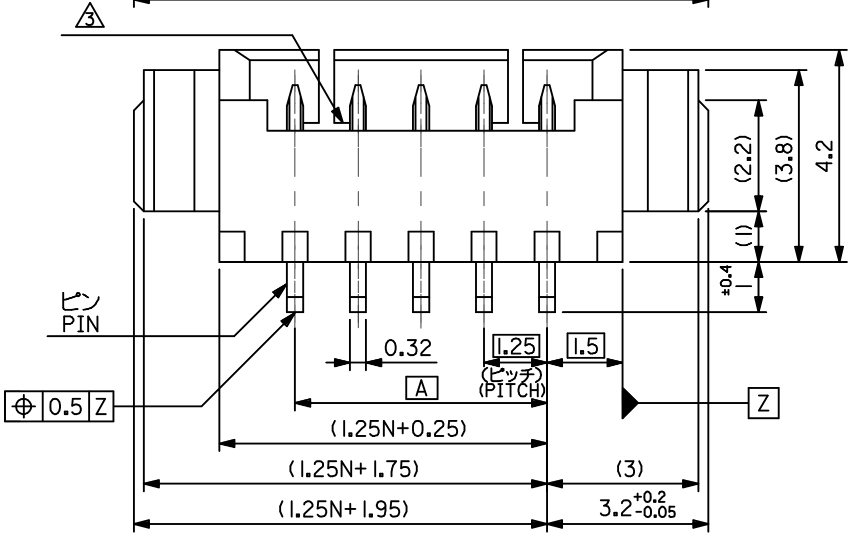
SIZE A3

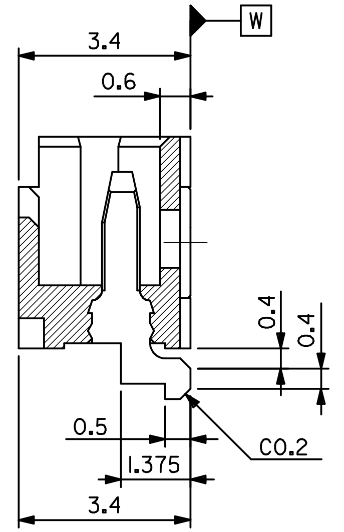




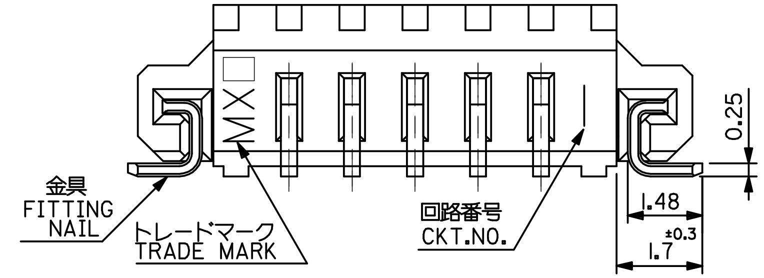
参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)

(SCALE 5:1)





[断面図]
[CROSS SECTION]



注記 NOTES

1. 嵌合相手： 51021シリーズ
   MATES WITH: 51021 SERIES
2. 材質 MATERIAL
   ウエハー ：NYLON46, UL94V-0
   ピン ：リン青銅
   PIN ：PHOS-BRO
   ：錫メッキ 1。0マイクロメートル以上
   :TIN 1.0 MICROMETER MINIMUM
   ：ニッケル下地 1。0マイクロメートル以上
   :NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
   金具 ：リン青銅
   FITTING NAIL ：PHOS-BRO
   ：錫メッキ 1。0マイクロメートル以上
   :TIN 1.0 MICROMETER MINIMUM
   ：ニッケル下地 1。0マイクロメートル以上
   :NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
3. ロック窓は2、3極は1箇所、4極以上は2箇所とする。
   LOCKING WINDOW : ONE PLACE FOR 2 AND 3 CKT. AND
   TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダーテール部のズレ量及び金具（補強板）のズレ量は基準面 W に対し、上方向 0.05 MAX.、下方向に0.1 MAX.とする。 W
   OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM :
   UPPER SIDE : 0.05MAX.
   LOWER SIDE : 0.1MAX.
5. 本製品は 53261ー＊＊10 の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 53261-**10
6. ELV及びRoHS適合品
   ELV AND RoHS COMPLIANT.

MODEL NO.	E	D	C	B	A	EMBOSSED TAPE PKG ORDER No.	MATERIAL. NO.	極数 CKT.
	26.4	26	23	21.8	20	53261-1771	53261-1719	17
	23.9	23.5	20.5	19.3	17.5	-1571	-1519	15
	22.65	22.25	19.25	18.05	16.25	-1471	-1419	14
	21.4	21	18	16.8	15	-1371	-1319	13
	20.15	19.75	16.75	15.55	13.75	-1271	-1219	12
	18.9	18.5	15.5	14.3	12.5	-1171	-1119	11
	17.65	17.25	14.25	13.05	11.25	-1071	-1019	10
	16.4	16	13	11.8	10	-0971	-0919	9
	15.15	14.75	11.75	10.55	8.75	-0871	-0819	8
	13.9	13.5	10.5	9.3	7.5	-0771	-0719	7
	12.65	12.25	9.25	8.05	6.25	-0671	-0619	6
	11.4	11	8	6.8	5	-0571	-0519	5
	10.15	9.75	6.75	5.55	3.75	-0471	-0419	4
	8.9	8.5	5.5	4.3	2.5	-0371	-0319	3
53261-**19	7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2

REV	DESCRIPTION
H	REVISED EC NO: J2015-0640 DRWN:YWAKE 2014/11/12 CH'KD:KASAKAWA 2014/11/12 APPR:NUKITA 2014/11/17

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

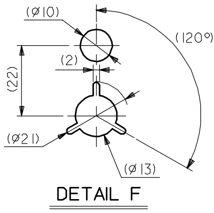
DIMENSION STYLE: MM ONLY
SCALE: 10:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: HSHIMABU DATE: 04/02/06
CHECKED BY: KTOJO DATE: 04/02/06
APPROVED BY: MSASAO DATE: 04/02/06

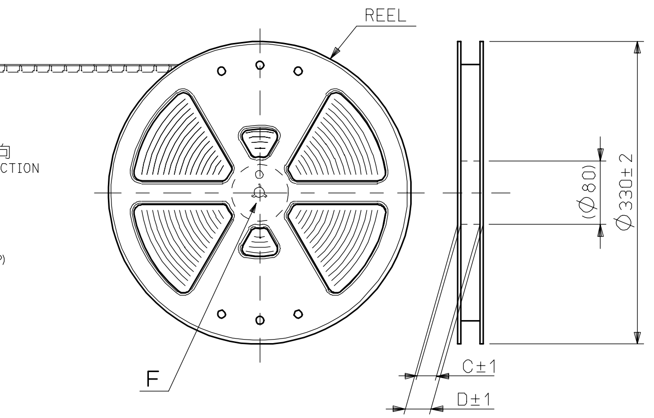
TITLE
1.25 WIRE TO BOARD
WAFER ASS FOR SMT

molex

MATERIAL NO.: SEE DRAWING
DOCUMENT NO.: SD-53261-024
SHEET NO.: 1 OF 1
SIZE: A3



DETAIL F



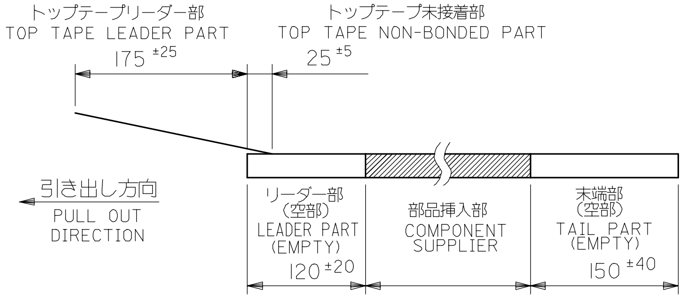
引き出し方向
PULL OUT DIRECTION

注記
NOTES

1. 5326I-**I9 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS,SEE SD-53261-024

2. 梱包数量：１０００個／リール
NUMBER OF CONNECTOR:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



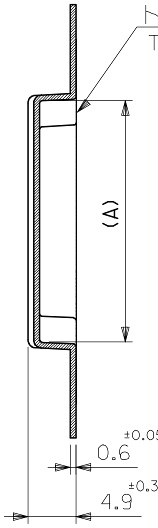
4. 材料 (MATERIAL)
キャリアテープ(CARRIER TAPE):ポリプロピレン(POLYPROPYLENE)
トップテープ (TOP TAPE): PET ,PE ,PEF
リール (REEL):ポリスチレン（ＰＳ）＜リサイクル材含む＞
POLYSTYREN(PS)＜RECYCLE MATERIAL CONTAINED＞

5. コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

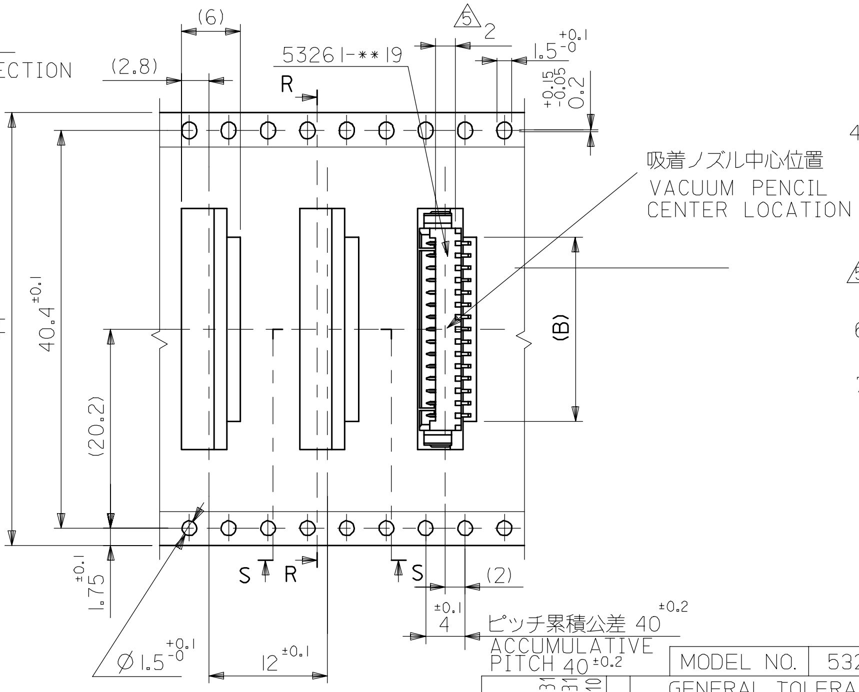
6. 本製品は、シリカゲル入りポリ袋梱包とする。SPK-53261-002参照。
THIS PRODUCT IS SILICAGEL PACKAGE. SEE SPK-53261-002.

7. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

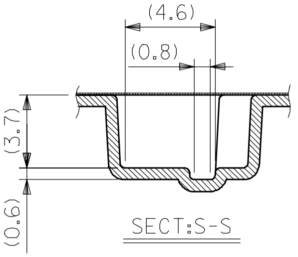
引き出し方向
PULL OUT DIRECTION



SECT:R-R



44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



SECT:S-S

44	49.4	45.4	21.2	27.0	53261-1771	17
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL. NO.	極数 CKT.

MODEL NO. 53261-**71

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

REV	DESCRIPTION
0	RELEASED EC NO: J2008-0056 DRWN:KSAIT001 2007/07/31 CH'KD:THARUYAMA 2007/07/31 APPR:NUKITA 2007/08/10

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	K.SAITO	2007/07/06
CHECKED BY	T.HARUYAMA	2007/07/06
APPROVED BY	N.UKITA	2007/07/06

TITLE
1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG

MOLEX INCORPORATED

MATERIAL NO. SEE TABLE
DOCUMENT NO. SD-53261-048
SHEET NO. 1 OF 1
SIZE A3